

MR750 SERIES

MR754 and MR760 are Preferred Devices

High Current Lead Mounted Rectifiers

Features

- Current Capacity Comparable to Chassis Mounted Rectifiers
- Very High Surge Capacity
- Insulated Case
- Pb-Free Packages are Available*

Mechanical Characteristics:

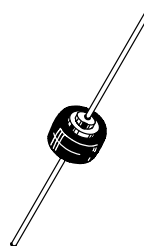
- Case: Epoxy, Molded
- Weight: 2.5 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Lead is Readily Solderable
- Lead Temperature for Soldering Purposes:
260°C Max. for 10 Seconds
- Polarity: Cathode Polarity Band
- Shipped 1000 units per plastic bag. Available Tape and Reeled, 800 units per reel by adding a "RL" suffix to the part number



ON Semiconductor®

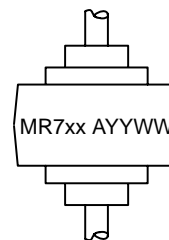
<http://onsemi.com>

**HIGH CURRENT
LEAD MOUNTED
SILICON RECTIFIERS
50 – 1000 VOLTS
DIFFUSED JUNCTION**



**AXIAL LEAD
BUTTON
CASE 194
STYLE 1**

MARKING DIAGRAM



MR7 = Device Code
xx = 50, 51, 52, 54, 56 or 60
A = Location Code
YY = Year
WW = Work Week

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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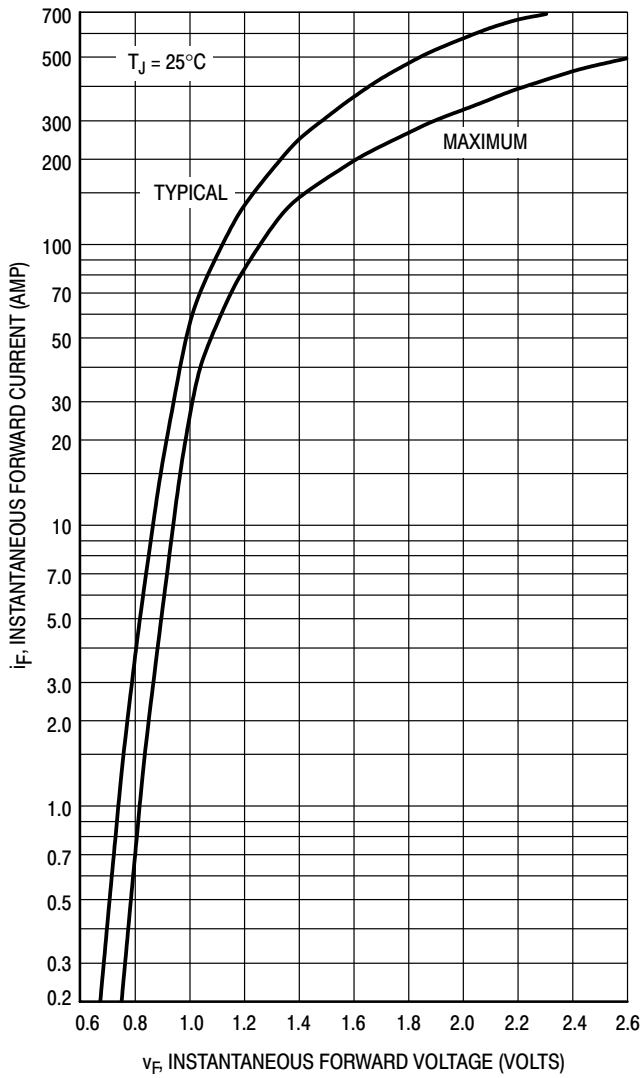


Figure 1. Forward Voltage

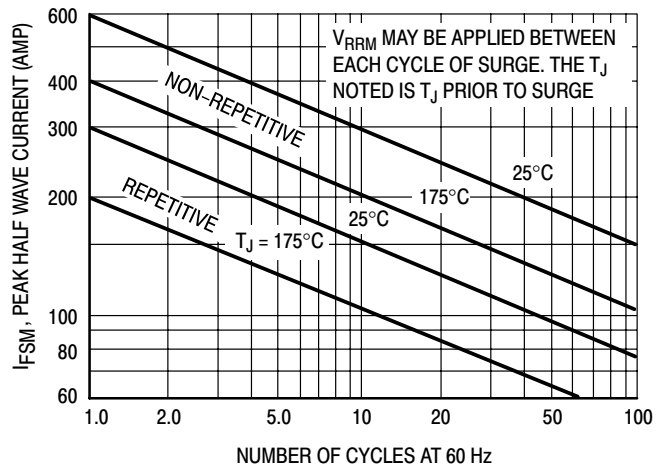


Figure 2. Maximum Surge Capability

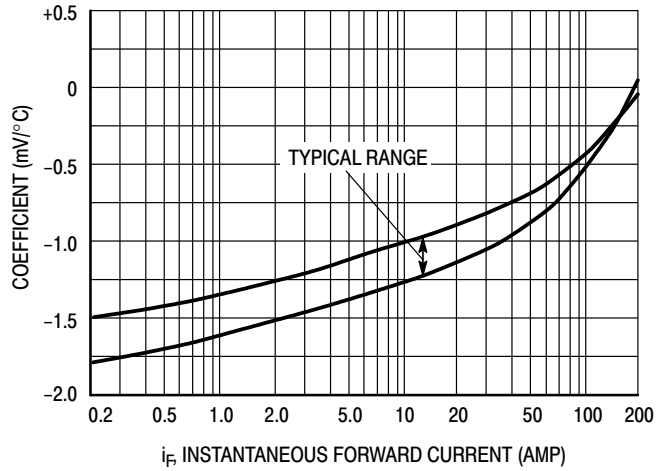


Figure 3. Forward Voltage Temperature Coefficient

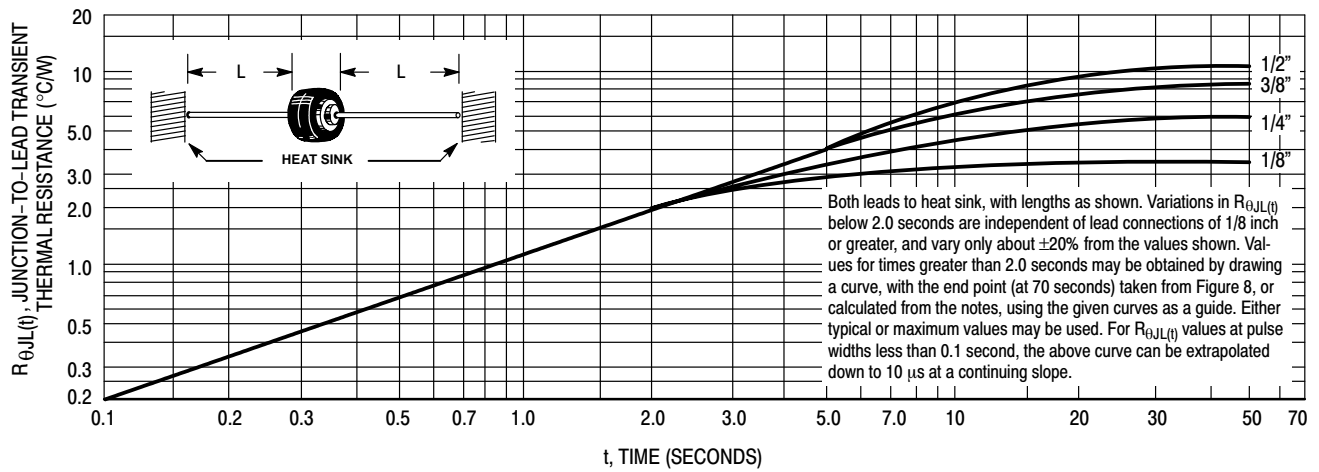


Figure 4. Typical Transient Thermal Resistance

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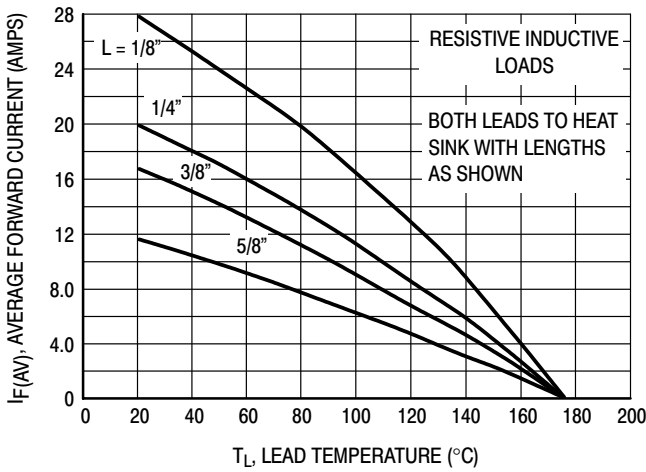


Figure 5. Maximum Current Ratings

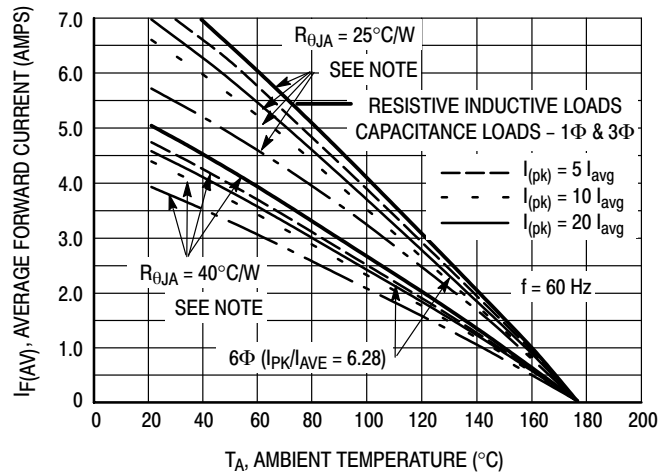


Figure 6. Maximum Current Ratings

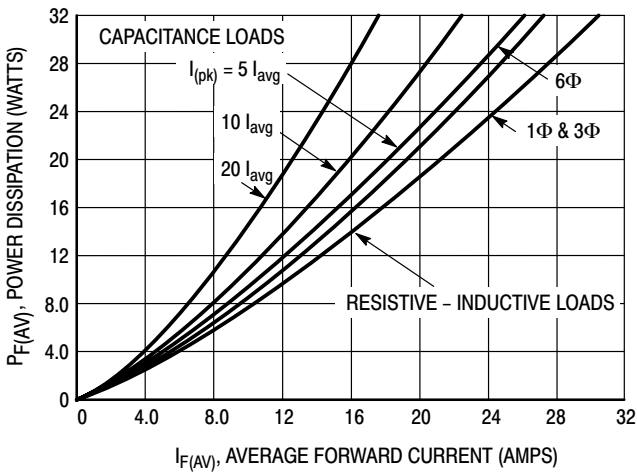


Figure 7. Power Dissipation

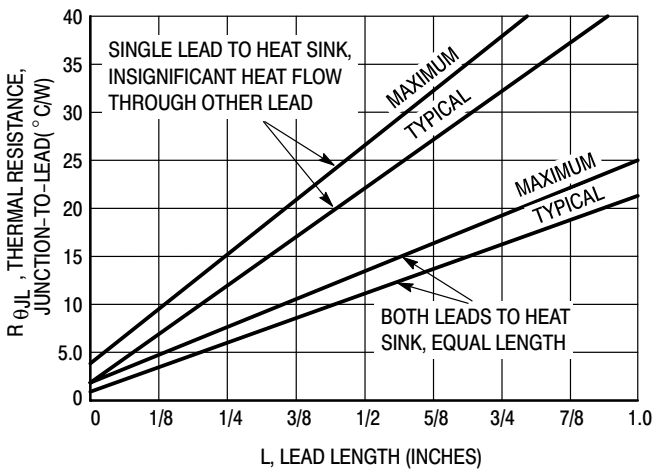
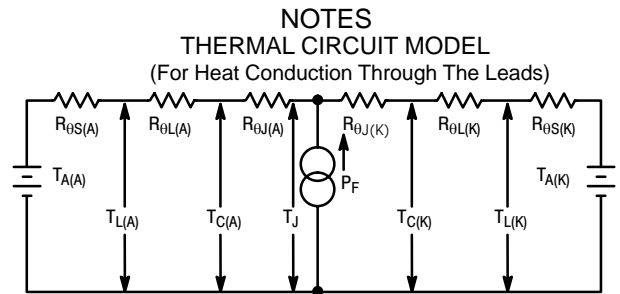


Figure 8. Steady State Thermal Resistance



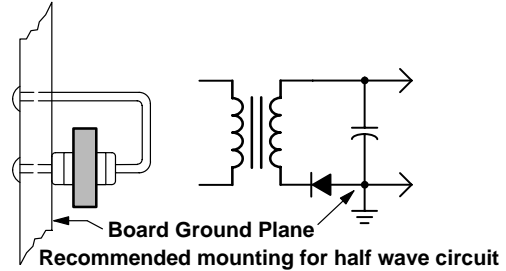
Use of the above model permits junction to lead thermal resistance for any mounting configuration to be found. Lowest values occur when one side of the rectifier is brought as close as possible to the heat sink as shown below. Terms in the model signify:

- T_A = Ambient Temperature
- T_L = Lead Temperature
- $R_{\theta S}$ = Thermal Resistance, Heat Sink to Ambient
- $R_{\theta L}$ = Thermal Resistance, Lead to Heat Sink
- $R_{\theta J}$ = Thermal Resistance, Junction to Case
- P_F = Power Dissipation
- T_C = Case Temperature
- T_J = Junction Temperature

(Subscripts A and K refer to anode and cathode sides, respectively.)
 Values for thermal resistance components are:
 $R_{\theta L} = 40^\circ\text{C/W/in.}$ Typically and 44°C/W/in. Maximum.
 $R_{\theta J} = 2^\circ\text{C/W}$ typically and 4°C/W Maximum.

Since $R_{\theta J}$ is so low, measurements of the case temperature, T_C , will be approximately equal to junction temperature in practical lead mounted applications. When used as a 60 Hz rectifier the slow thermal response holds $T_{J(pk)}$ close to $T_{J(ave)}$. Therefore maximum lead temperature may be found from: $T_L = 175^\circ - R_{\theta JL} P_F$. P_F may be found from Figure 7.

The recommended method of mounting to a P.C. board is shown on the sketch, where $R_{\theta JA}$ is approximately 25°C/W for a $1-1/2" \times 1-1/2"$ copper surface area. Values of 40°C/W are typical for mounting to terminal strips or P.C. boards where available surface area is small.



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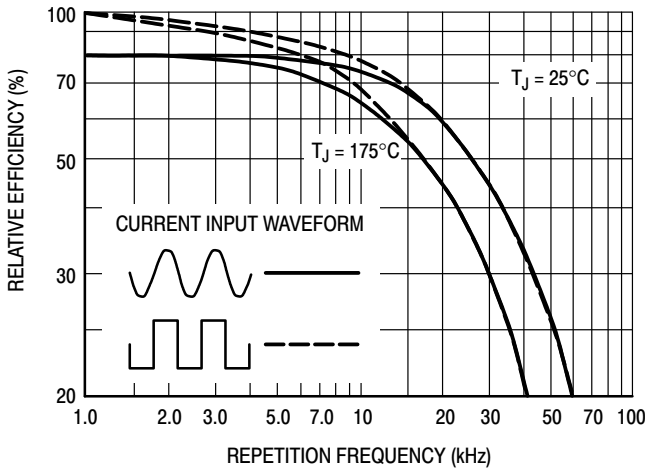


Figure 9. Rectification Efficiency

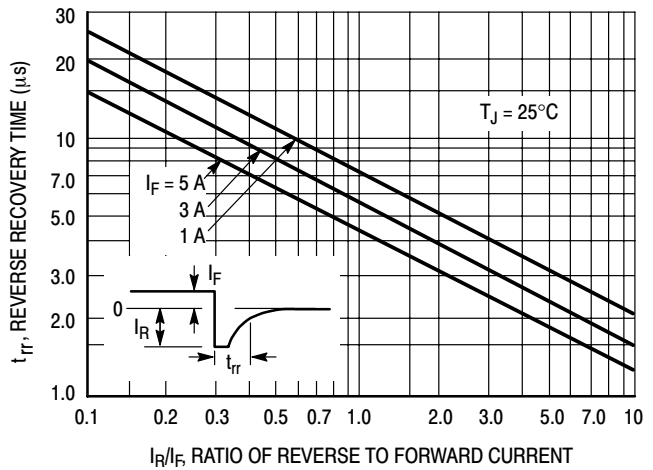


Figure 10. Reverse Recovery Time

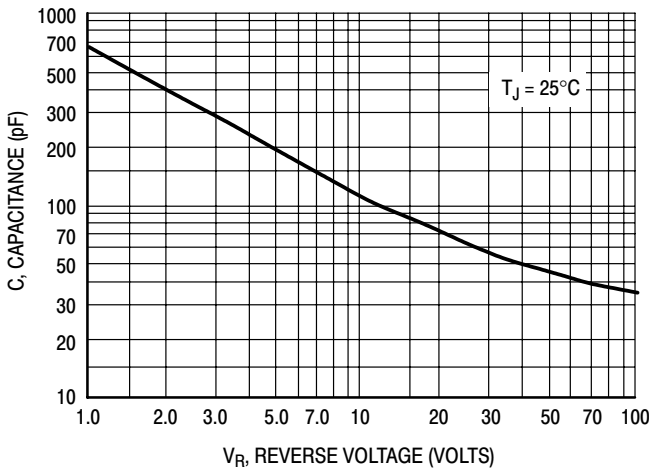


Figure 11. Junction Capacitance

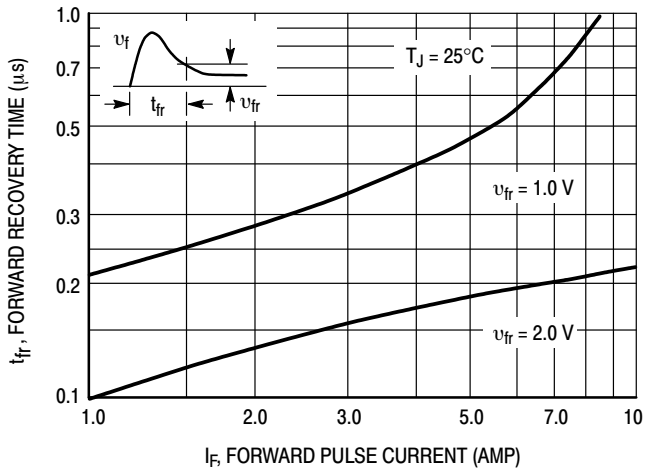


Figure 12. Forward Recovery Time

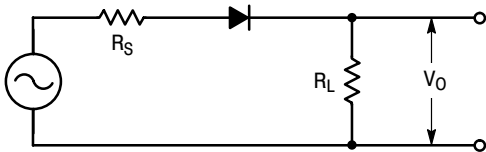


Figure 13. Single-Phase Half-Wave Rectifier Circuit

The rectification efficiency factor σ shown in Figure 9 was calculated using the formula:

$$\sigma = \frac{P_{(dc)}}{P_{(rms)}} = \frac{\frac{V_{2O}(dc)}{R_L}}{\frac{V_{2O}(rms)}}{R_L}} \cdot 100\% = \frac{V_{2O}(dc)}{V_{2O}(ac) + V_{2O}(dc)} \cdot 100\% \quad (1)$$

For a sine wave input $V_m \sin(\omega t)$ to the diode, assumed lossless, the maximum theoretical efficiency factor becomes:

$$\sigma_{(sine)} = \frac{\frac{V_{2m}}{\pi^2 R_L}}{\frac{V_{2m}}{4R_L}} \cdot 100\% = \frac{4}{\pi^2} \cdot 100\% = 40.6\% \quad (2)$$

For a square wave input of amplitude V_m , the efficiency factor becomes:

$$\sigma_{(square)} = \frac{\frac{V_{2m}}{2R_L}}{\frac{V_{2m}}{R_L}} \cdot 100\% = 50\% \quad (3)$$

(A full wave circuit has twice these efficiencies)

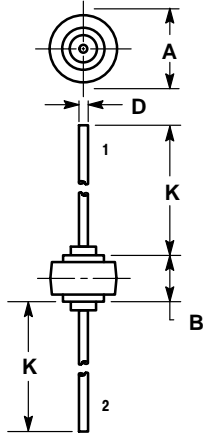
As the frequency of the input signal is increased, the reverse recovery time of the diode (Figure 10) becomes significant, resulting in an increasing AC voltage component across R_L which is opposite in polarity to the forward current, thereby reducing the value of the efficiency factor σ , as shown on Figure 9.

It should be emphasized that Figure 9 shows waveform efficiency only; it does not provide a measure of diode losses. Data was obtained by measuring the AC component of V_o with a true rms AC voltmeter and the DC component with a DC voltmeter. The data was used in Equation 1 to obtain points for Figure 9.

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PACKAGE DIMENSIONS


AXIAL LEAD BUTTON CASE 194-04 ISSUE H



- NOTES:
1. CATHODE SYMBOL ON PACKAGE.
 2. 194-01 OBSOLETE, 194-04 NEW STANDARD.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.43	8.69	0.332	0.342
B	5.94	6.25	0.234	0.246
D	1.27	1.35	0.050	0.053
K	25.15	25.65	0.990	1.010

- STYLE 1:
PIN 1. CATHODE
2. ANODE

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